

Application Number: 10/654,167

Dkt. No.: DT-024-US-01

Listing of Claims

- 1.(Currently Amended) A hot melt adhesive composition comprising:
- (a) an ethylene methyl methacrylate copolymer having a peak melting point of no greater than about $67^{\circ}\text{C} \pm 6^{\circ}\text{C}$;
 - (b) a wax; and
 - (c) a tackifying resin,
- with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.
- 2.(Original) The composition of claim 1 further comprising an oil.
- 3.(Cancelled)
- 4.(Currently amended) The composition of claim [[2]] 1 further comprising an antioxidant.
- 5.(Currently amended) The composition of claim [[4]] 1 further comprising a copolymer.
- 6.(Currently amended) The composition of claim [[5]] 1 further comprising a block copolymer.
- 7.(Cancelled)
- 8.(Canceled)
- 9.(Original) A package formulation comprising:
- (a) the composition of claim 1; and
 - (b) instructions for application of the composition to a substrate.

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10.(canceled)

11.(Currently Amended) A hot melt adhesive composition consisting essentially of:

- (a) an autoclave reactor ethylene methyl methacrylate copolymer;
- (b) a wax; and
- (c) a tackifying resin.

12.(Original) The composition of claim 11 further consisting essentially of an oil.

13.(Cancelled)

14.(Currently amended) The composition of claim ~~[[12]]~~ 11 further consisting essentially of an antioxidant.

15.(canceled)

16.(Cancelled)

17.(Original) The composition of claim 11 further consisting essentially of a block copolymer.

18.(canceled)

19.(Withdrawn) A method of using a hot melt adhesive composition comprising:

- (a) providing a hot melt adhesive composition comprising:
 - (i) an ethylene methyl methacrylate copolymer having a peak melting point of no greater than about 67°C ± 6°C; and
 - (ii) a tackifying resin,

with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate; and

- (b) applying the composition to a substrate.

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20.(Withdrawn) The method of claim 19 wherein the method is a method of using the hot melt adhesive for book binding.

21. (New) A hot melt adhesive composition comprising:

- (a) an ethylene methyl methacrylate copolymer,
- (b) a tackifying resin,
- (c) a wax
- (d) a copolymer,

with the proviso that the composition does not include a surfactant or a copolymer of ethylene and n-butyl acrylate.

22. (New) The hot melt adhesive composition of claim 21, wherein said copolymer is a block copolymer.

23. (New) The hot melt adhesive composition of claim 21, wherein said copolymer is chosen from ethylene vinyl acetate, ethylene methyl acrylate, ethylene ethyl acrylate, interpolymers, or mixtures thereof.

24. (New) The hot melt adhesive composition of claim 21, further comprising oil.

25. (New) The composition of claim 21, further comprising an antioxidant.